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Docket No.: 20140-0281-US  
(PATENT)

1765/C  
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IN THE UNITED STATES PATENT AND TRADEMARK OFFICE

In re Patent Application of:  
Timothy S. Chamberlin, et al.

Conf. No. 6572

Application No.: 09/819,787

Group Art Unit: 1765

Filed: March 29, 2001

Examiner: S. Ahmed

For: SLURRY AND USE THEREOF FOR  
POLISHING

AMENDMENT UNDER 37 CFR 1.111

Commissioner for Patents  
Washington, DC 20231

Dear Sir:

In response to the Office Action dated December 19, 2002 (Paper No. 4), please amend the above-identified U.S. Patent application as follows:

In the Claims

Please amend claim 19 to read as follows:

19. (Amended) A method for polishing a surface, comprising:
- providing on said surface a slurry comprising abrasive particles and an oxidizing agent wherein said oxidizing agent has a static etch rate on metal of less than 1000Å per hour; and wherein the pH of the slurry is about 5 to about 11;
- and polishing said surface by contacting it with a polishing pad.